

REMARKS

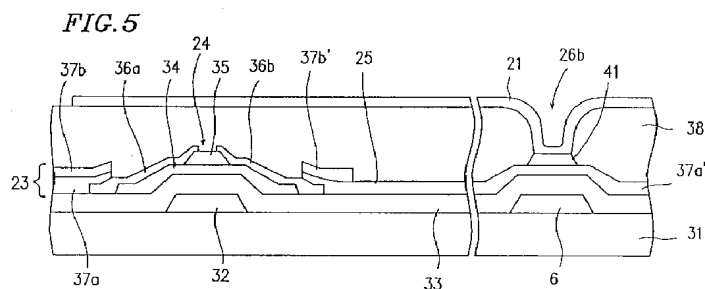
At the outset, the Examiner is thanked for the thorough review and consideration of the pending application. The Office Action dated June 11, 2010 has been received and its contents carefully reviewed.

Applicant has amended claim 1. No new matter has been added. Thus, claims 1-9 and 11-27 are currently pending with claims 11-26 having been withdrawn from consideration. Applicant respectfully requests reconsideration of pending claims.

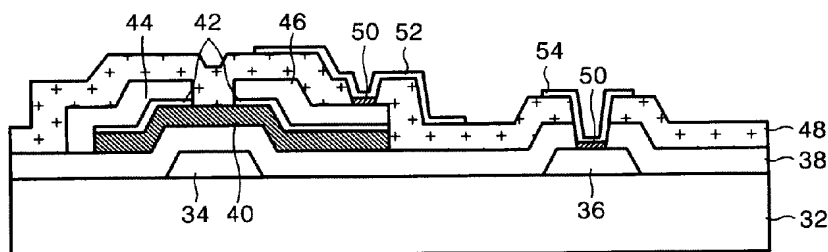
The Office Action objects claim 1 because of informalities. Also, the Office Action rejects claims 1-9 and 27-28 under 35 U.S.C. 103(a) as being unpatentable over Applicant's Admitted Prior Art (hereinafter "APA"). Applicants respectfully point out that it appears that the Examiner is rejecting claims 1-9 and 27-28 over APA in view of U.S. Patent No. 6,188,458 to Tagusa ("Tagusa"). Applicant respectfully traverses the rejections.

Claim 1, as amended, is allowable over the cited references in that claim 1 recites a combination of elements including, for example, "a first adhesion conductive layer on the exposed portion of a third conductive layer and a second adhesion conductive layer on the exposed portion of the pad layer, wherein the first adhesion conductive layer is directly contacted with the third conductive layer and the second adhesion conductive layer is directly contacted with the pad layer; a fourth conductive layer on the second insulating layer and the first adhesion conductive layer and electrically contacting a portion of a third conductive layer; a fifth conductive layer on the second insulating layer and the second adhesion conductive layer and electrically contacting the pad layer, wherein the first and second adhesion conductive layers are respectively contained within the first contact hole and in the second contact hole" None of the cited references, singly or in combination, teaches or suggests at least this feature of the claim 1. The Examiner admits that the APA does not teach this feature and cites Tagusa as teaching this feature.

In Tagusa, the "metal nitride layer 41 is formed on the portion of the transparent film 37a' under each contact hole 26b." Tagusa 12:6-8. The metal layer 41 is not contacted with the common line 6.



However, Fig. 3E of our disclosure does show that wherein the first adhesion conductive layer 50 is directly contacted with the third conductive layer 46 as the drain electrode of TFT and the second adhesion conductive layer 50 is directly contacted with the pad layer 36.



Also, Figure 5 of Tagusa does not show that the first adhesion conductive layer is contacted with the third conductive layer corresponding with the drain electrode of TFT.

For at least this reason, Applicant submits that claim 1 and claims 2-9 and 27, which depend therefrom, are allowable over the cited references.

Applicants believe the application is in condition for allowance and early, favorable action is respectfully solicited.

If for any reason the Examiner finds the application other than in condition for allowance, the Examiner is requested to call the undersigned attorney at (202) 496-7500 to discuss the steps necessary for placing the application in condition for allowance. All correspondence should continue to be sent to the below-listed address.

If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time, or any other fees required to complete the filing of this response, may be charged to Deposit Account No. 50-0911. Please credit any overpayment to deposit Account No. 50-0911.

Dated: September 10, 2010

Respectfully submitted,

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